HIGH-SIDE AND LOW-SIDE GATE DRIVERS IN SO-16 (TYPE TH)

Description

The DGD2110 and DGD2113 are high-voltage / high-speed MOSFET and IGBT drivers with independent high-side and low-side outputs. The high-side driver features floating supply for operation at up to 500V/600V. The 10ns (max) / 20ns (max) propagation delay matching between the high and the low side drivers allows high-frequency operation.

The DGD2110 and DGD2113 logic inputs are compatible with standard CMOS levels (as low as 3.3V) while driver outputs feature high-pulse current buffers designed for minimum driver cross conduction.

The DGD2110 and DGD2113 are offered in a 16-pin SO (Type TH) package. They operate over an extended -40°C to +125°C temperature range.

Features

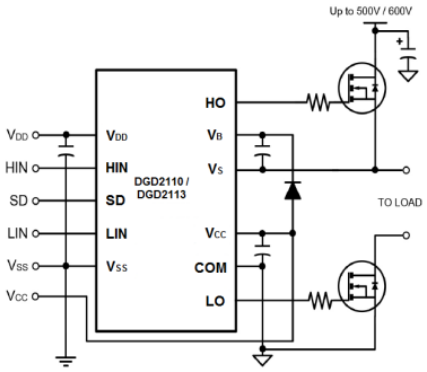
- Drives two N-Channel MOSFETs or IGBTs in high-side/low-side configuration
- Floating high-side operates to 600V
- 2.5A sink / 2.5A source typical output currents
- Outputs tolerant to negative transients
- Wide gate driver supply voltage range: 10V to 20V
- Wide logic input supply voltage range: 3.3V to 20V
- Wide logic supply offset voltage range: -5V to 5V
- 15ns (typ) rise / 13ns (typ) fall times with 1000pF load
- 105ns (typ) turn-on / 94ns (typ) turn-off delay times
- Cycle-by-cycle edge-triggered shutdown circuitry
- Extended temperature range: -40°C to +125°C
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony free. "Green" Device (Note 3)**

Applications

- DC-DC Converters
- DC-AC Inverters
- AC-DC Power Supplies
- Motor Controls
- Class D Power Amplifiers

Mechanical Data

- Case: SO-16 (Type TH)
- Case Material: Molded Plastic. "Green" Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 (e3)
- Weight: 0.130 grams (Approximate)



Typical Configuration

SO-16 (Type TH)
Top View

Ordering Information (Note 4)

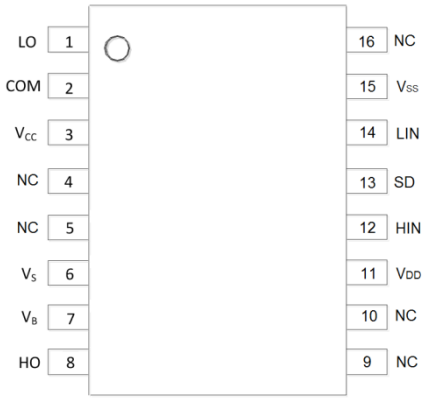
Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DGD2110S16-13	DGD2110	13	16	1,500
DGD2113S16-13	DGD2113	13	16	1,500

Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

= Manufacturer's Marking
DGD211x = Product Type Marking Code (See Table Above)
YY = Year (ex: 16 = 2016)
WW = Week (01 - 53)

Pin Diagrams

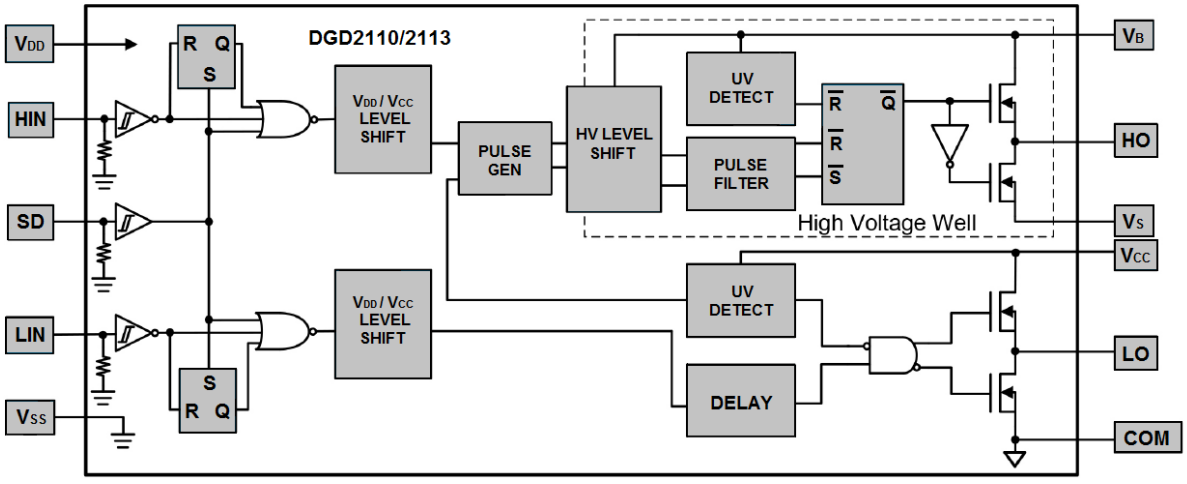


Top view: SO-16 (Type TH)

Pin Descriptions

Pin Number	Pin Name	Function
1	LO	Low-side gate driver output pin
2	COM	Low-side gate driver power supply return pin
3	V_{CC}	Low-side gate driver power supply pin
4,5,9,10,16	NC	"No connect" pin (No Internal Connection)
6	V_S	High-side gate driver floating power supply return pin
7	V_B	High-side gate driver floating power supply pin
8	HO	High-side gate drive output pin
11	V_{DD}	Logic power supply pin
12	HIN	Logic input pin for high-side gate driver output. HIN and HO are in phase
13	SD	Logic input shutdown pin
14	LIN	Logic input pin for low-side gate driver output. LIN and LO are in phase
15	V_{SS}	Logic ground pin

Functional Block Diagram



Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
High-side floating supply voltage (DGD2110)	V_B	-0.3 to +524	V
High-side floating supply voltage (DGD2113)	V_B	-0.3 to +624	V
High-side floating supply offset voltage	V_S	V_B-24 to V_B+0.3	V
High-side floating output voltage	V_{HO}	V_S-0.3 to V_S+0.3	V
Offset supply voltage transient	dV_S / dt	50	V/ns
Low-side fixed supply voltage	V_{CC}	-0.3 to +24	V
Low-side output voltage	V_{LO}	-0.3 to V_{CC}+0.3	V
Logic supply voltage	V_{DD}	-0.3 to V_{SS}+24	V
Logic supply offset voltage	V_{SS}	V_{CC}-24 to V_{CC}+0.3	V
Logic input voltage (HIN, LIN and SD)	V_{IN}	V_{SS}-0.3 to V_{DD}+0.3	V

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation Linear derating factor (Note 5)	P_D	1.25	W
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	90	°C/W
Thermal Resistance, Junction to Case (Note 5)	$R_{\theta JC}$	45	°C/W
Operating Temperature	T_J	+150	°C
Lead Temperature (soldering, 10 seconds)	T_L	+300	
Storage Temperature Range	T_{STG}	-55 to +150	

Note: 5. When mounted on a standard JEDEC 2-layer FR-4 board.

Recommended Operating Conditions

Parameter		Symbol	Min	Max	Unit
High-side floating supply absolute voltage		V_B	V_S + 10	V_S + 20	V
High-side floating supply offset voltage	DGD2110	V_S	(Note 6)	500	V
High-side floating supply offset voltage	DGD2113	V_S	(Note 6)	600	V
High-side floating output voltage		V_{HO}	V_S	V_B	V
Low-side fixed supply voltage		V_{CC}	10	20	V
Low-side output voltage		V_{LO}	0	V_{CC}	V
Logic supply voltage		V_{DD}	V_{SS} + 3	V_{SS} + 20	V
Logic supply offset voltage		V_{SS}	-5 (Note 7)	5	V
Logic input voltage (HIN, LIN and SD)		V_{IN}	V_{SS}	V_{DD}	V
Ambient temperature		T_A	-40	+125	°C

Notes: 6. Logic operation for V_S = -4V to +500V. Logic state held for V_S = -4V to -V_{BS}.
7. When V_{DD} <5V, the minumum V_{SS} offset is limited to -V_{DD}.

DC Electrical Characteristics (V_{BIAS} (V_{CC}, V_{BS}, V_{DD}) = 15V, V_{SS} = COM, @T_A = +25°C unless otherwise specified.) (Note 8)

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Logic "1" input voltage	V_{IH}	9.5	–	–	V	–
Logic "0" input voltage	V_{IL}	–	–	6.0	V	–
High level output voltage, V_{BIAS} - V_O	V_{OH}	–	–	1.4	V	I_O = 0mA
Low level output voltage, V_O	V_{OL}	–	–	0.15	V	I_O = 20mA
Offset supply leakage current	I_{LK}	–	–	50	µA	V_B = V_S = 500V/600V
Quiescent V_{BS} supply current	I_{BSQ}	–	55	230	µA	V_{IN} = 0V or V_{DD}
Quiescent V_{CC} supply current	I_{CCQ}	–	56	340	µA	V_{IN} = 0V or V_{DD}
Quiescent V_{DD} supply current	I_{DDQ}	–	0.6	30	µA	V_{IN} = 0V or V_{DD}
Logic "1" input bias current	I_{IN+}	–	20	40	µA	V_{IN} = V_{DD}
Logic "0" input bias current	I_{IN-}	–	–	5.0	µA	V_{IN} = 0V
V_{BS} supply undervoltage positive going threshold	V_{BSUV+}	7.5	8.6	9.7	V	–
V_{BS} supply undervoltage negative going threshold	V_{BSUV-}	7.0	8.2	9.4	V	–
V_{CC} supply undervoltage positive going threshold	V_{CCUV+}	7.4	8.5	9.6	V	–
V_{CC} supply undervoltage negative going threshold	V_{CCUV-}	7.0	8.2	9.4	V	–
Output high short circuit pulsed current	I_{O+}	2.0	2.5	–	A	V_O = 0V, V_{IN} = V_{DD}, PW ≤ 10µs
Output low short circuit pulsed current	I_{O-}	2.0	2.5	–	A	V_O = 15V, V_{IN} = 0V, PW ≤ 10µs

Note: 8. The V_{IN} and I_{IN} parameters are referenced to V_{SS} and are applicable to all three logic input pins: HIN, LIN and SD. The V_O and I_O parameters are referenced to COM and are applicable to the respective output pins: HO and LO.

AC Electrical Characteristics (V_{BIAS} (V_{CC}, V_{BS}, V_{DD}) = 15V, C_L = 1000pF, V_{SS} = COM, @T_A = +25°C, unless otherwise specified.)

Parameter		Symbol	Min	Typ	Max	Unit	Conditions
Turn-on propagation delay		t_{ON}	–	105	150	ns	V_S = 0V
Turn-off propagation delay		t_{OFF}	–	94	125	ns	V_S = 500V/600V
Shut down propagation delay		t_{SD}	–	70	140	ns	V_S = 500V/600V
Turn-on rise time		t_r	–	15	35	ns	–
Turn-off fall time		t_f	–	13	25	ns	–
Delay matching	DGD2110	t_{DM}	–	–	10	ns	–
Delay matching	DGD2113	t_{DM}	–	–	20	ns	–

Timing Waveforms

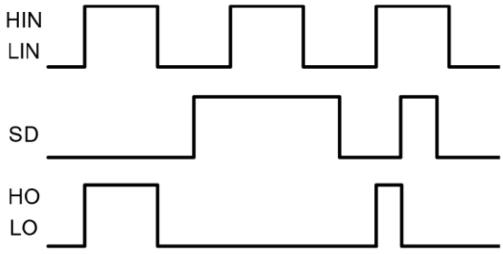


Figure 1. Input / Output Timing Diagram

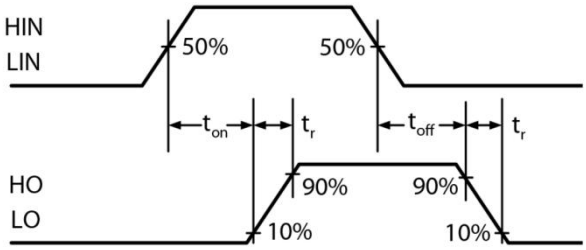


Figure 2. Switching Time Waveform Definitions

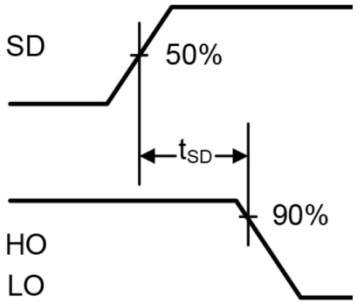


Figure 3. Shutdown Waveform Definitions

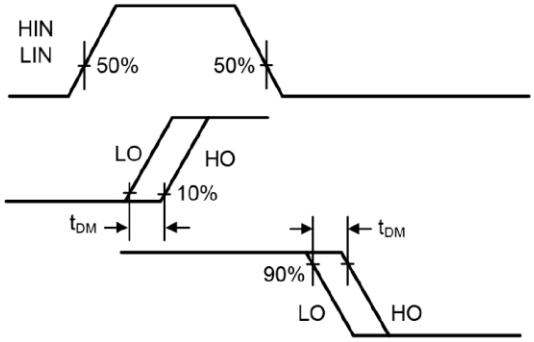


Figure 4. Delay Matching Waveform Definitions

Typical Performance Characteristics (@T_A = +25°C, unless otherwise specified.)

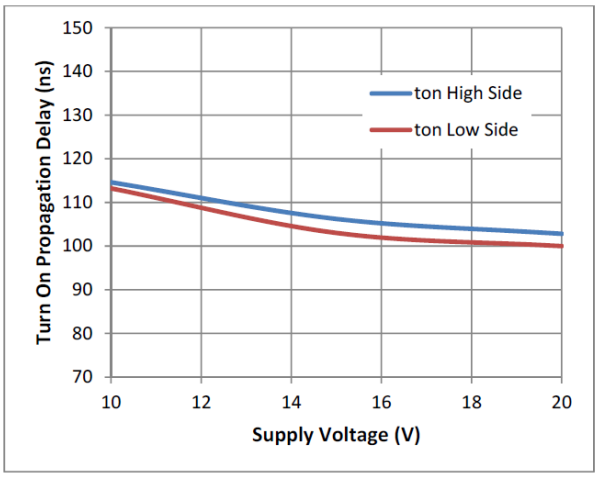


Figure 5. Turn-on Propogation Delay vs. Supply Voltage

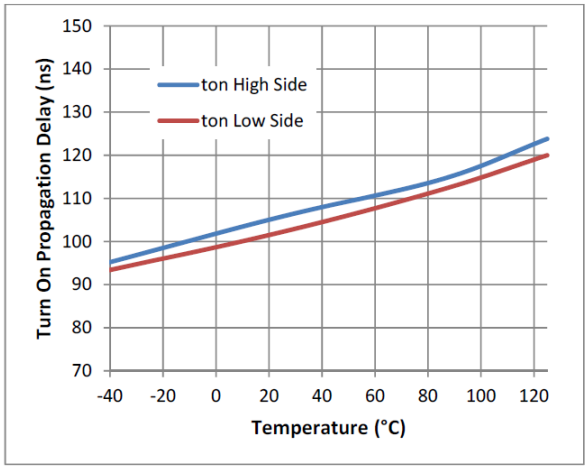


Figure 6. Turn-on Propogation Delay vs. Temperature

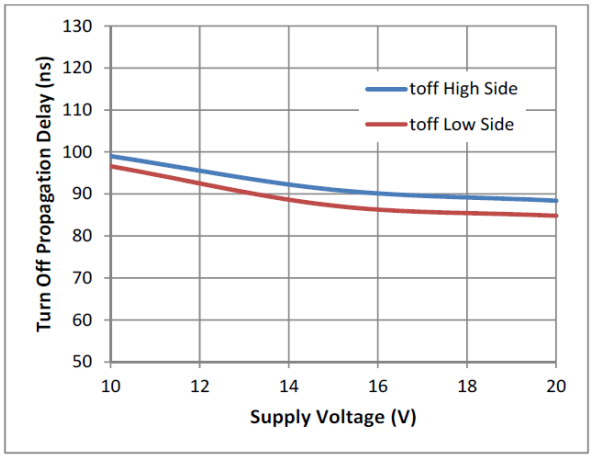


Figure 7. Turn-off Propogation Delay vs. Supply Voltage

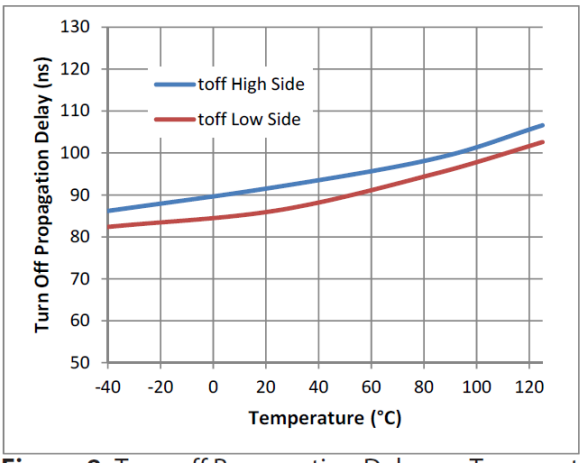


Figure 8. Turn-off Propogation Delay vs. Temperature

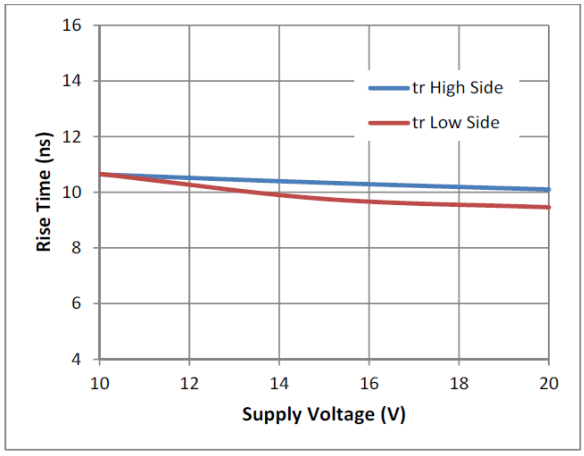


Figure 9. Rise Time vs. Supply Voltage

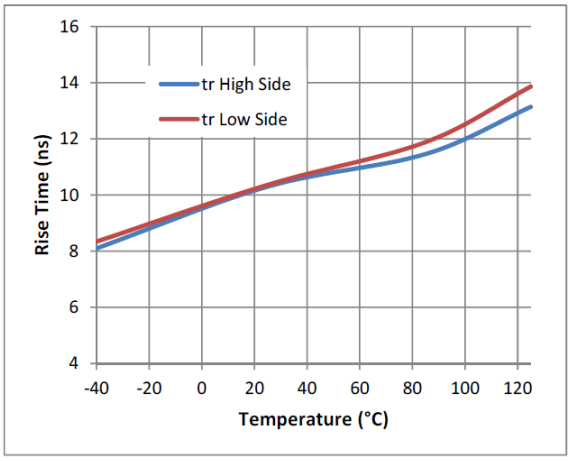


Figure 10. Rise Time vs. Temperature

Typical Performance Characteristics (continued)

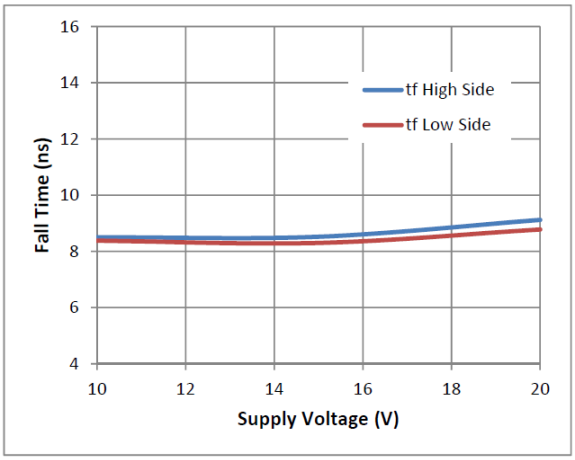


Figure 11. Fall Time vs. Supply Voltage

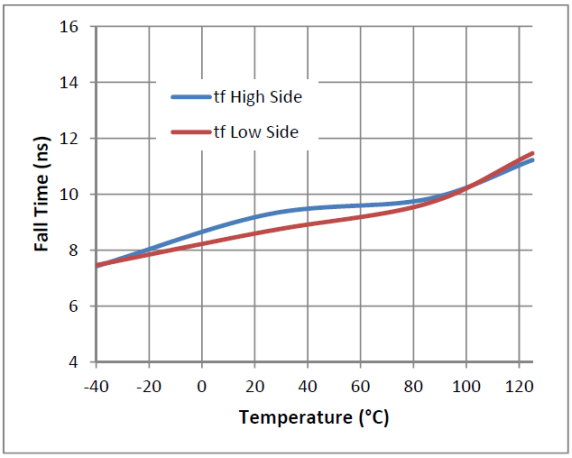


Figure 12. Fall Time vs. Temperature

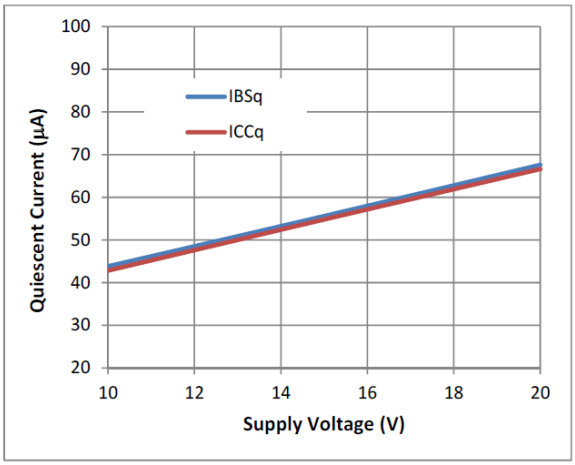


Figure 13. Quiescent Current vs. Supply Voltage

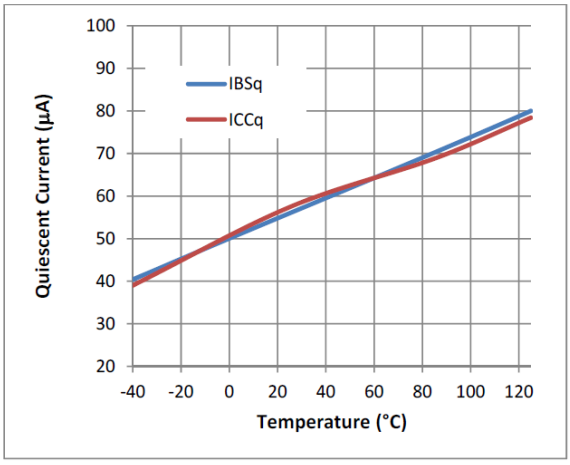


Figure 14. Quiescent Current vs. Temperature

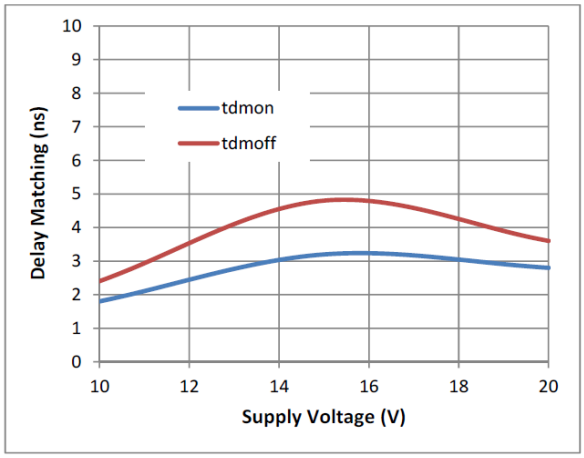


Figure 15. Delay Matching vs. Supply Voltage

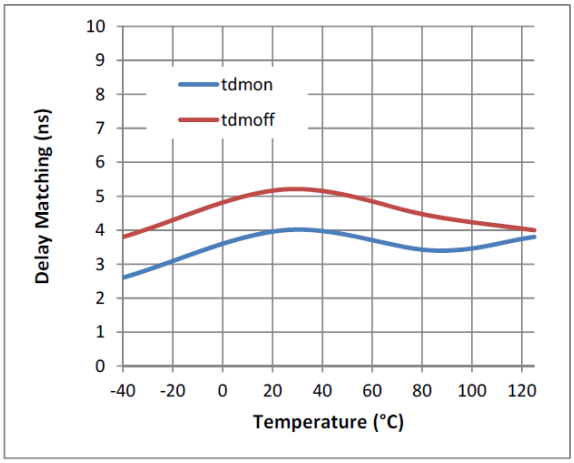


Figure 16. Delay Matching vs. Temperature

Typical Performance Characteristics (cont.)

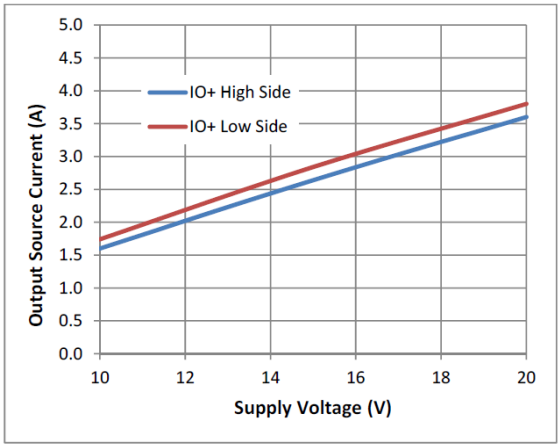


Figure 17. Output Source Current vs. Supply Voltage

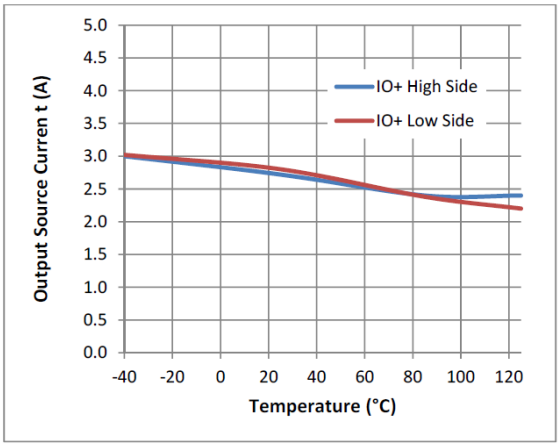


Figure 18. Output Source Current vs. Temperature

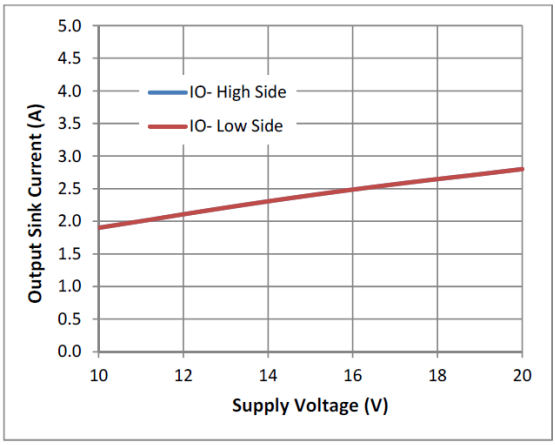


Figure 19. Output Sink Current vs. Supply Voltage

Note: graphs overlap one another

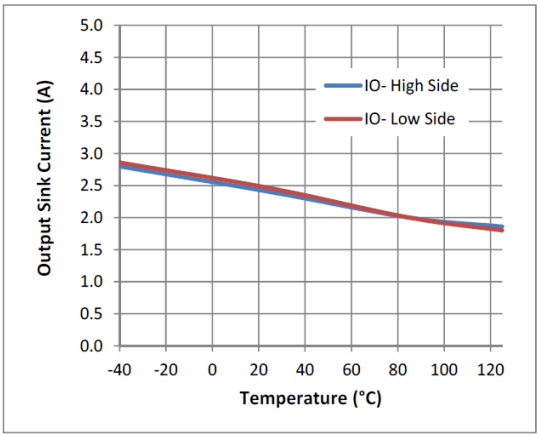


Figure 20. Output Sink Current vs. Temperature

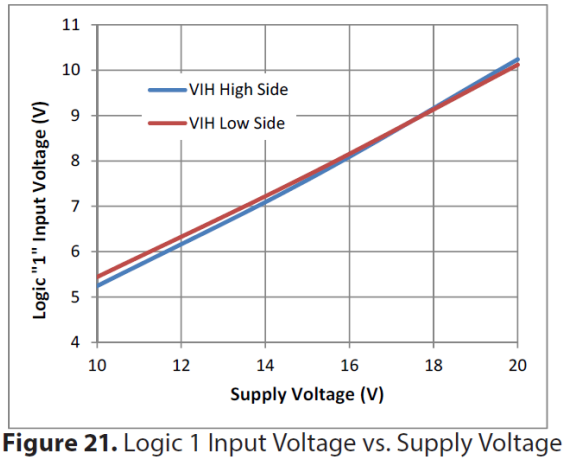


Figure 21. Logic 1 Input Voltage vs. Supply Voltage

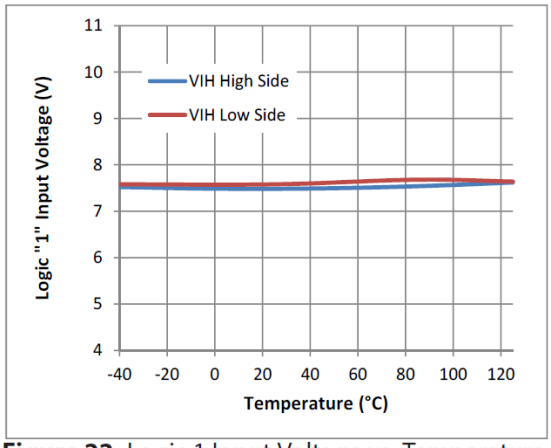


Figure 22. Logic 1 Input Voltage vs. Temperature

Typical Performance Characteristics (cont.)

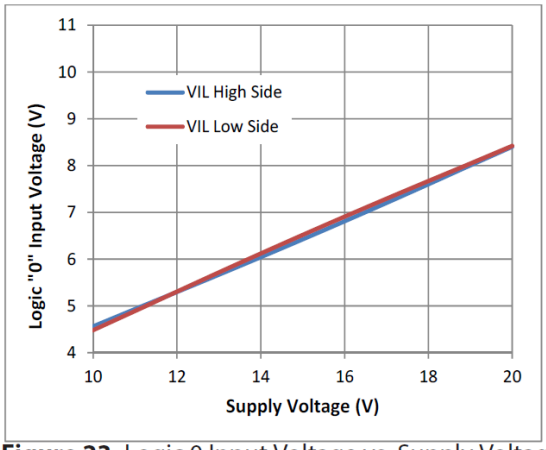


Figure 23. Logic 0 Input Voltage vs. Supply Voltage

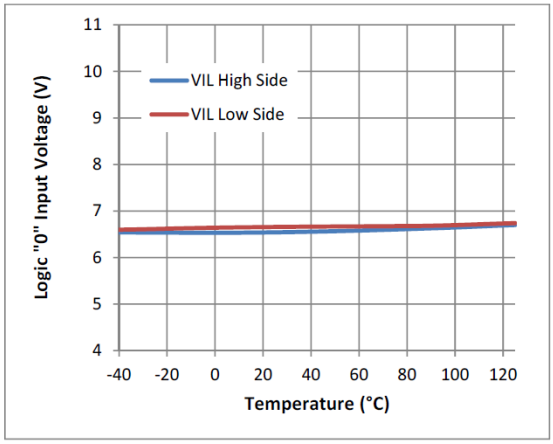


Figure 24. Logic 0 Input Voltage vs. Temperature

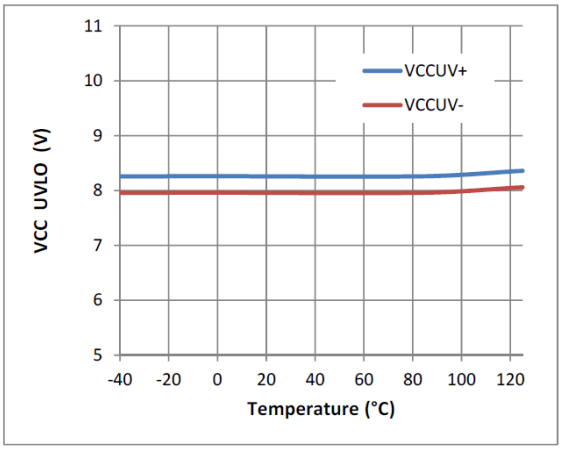


Figure 25. V_{CC} UVLO vs. Temperature

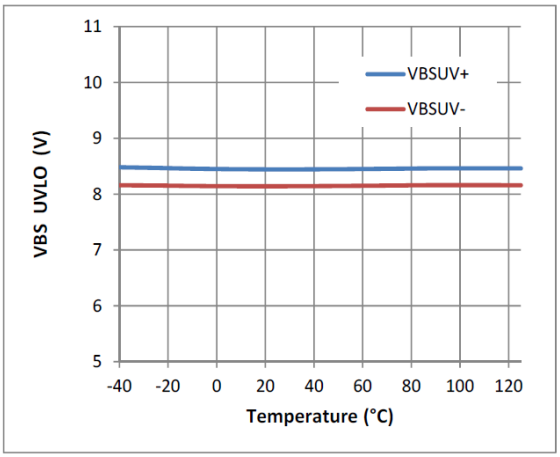


Figure 26. V_{BS} UVLO vs. Temperature

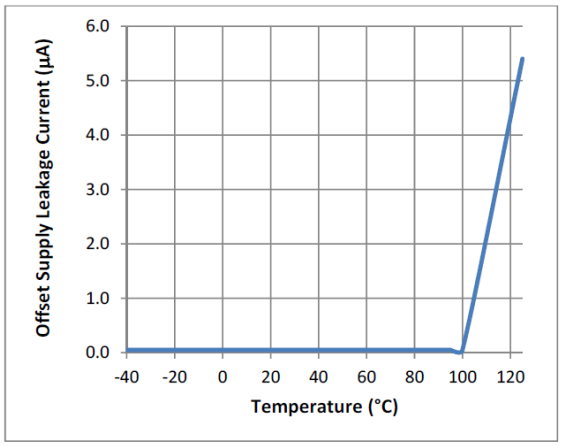


Figure 27. Offset Supply Leakage Current vs. Temperature

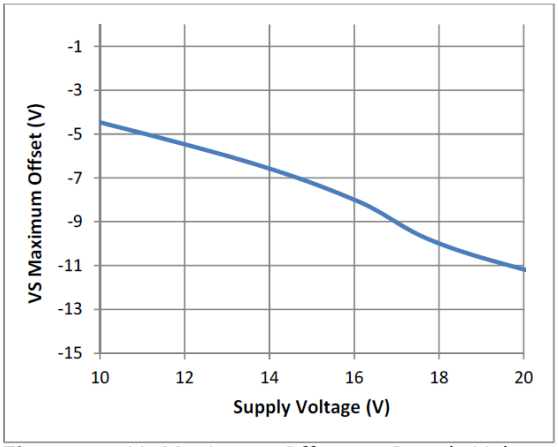


Figure 28. V_S Maximum Offset vs. Supply Voltage

Typical Performance Characteristics (cont.)

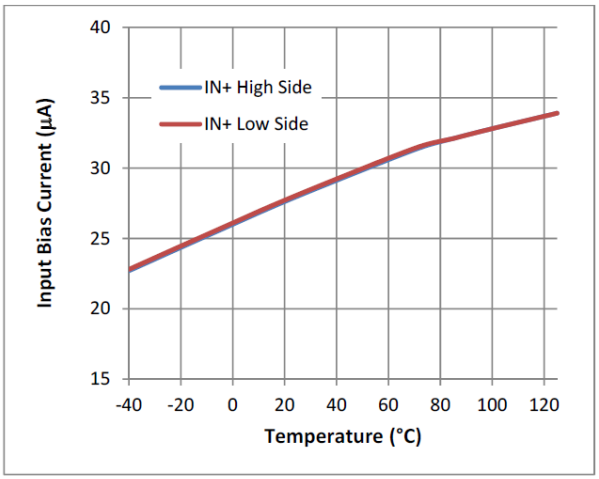
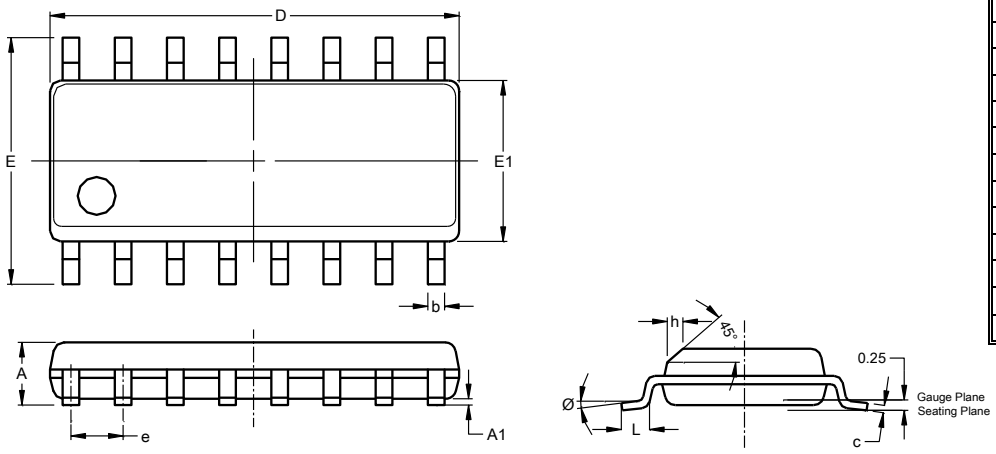


Figure 29. Input Bias Current vs. Temperature

Package Outline Dimensions

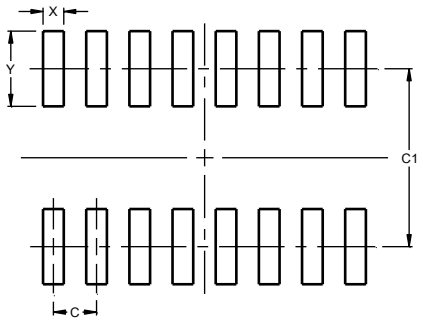
Please see AP02001 at http://www.diodes.com/_files/datasheets/ap02001.pdf for the latest version.



SO-16 (Type TH)			
Dim	**Min**	**Max**	**Typ**
A	2.36	2.64	--
A1	0.10	0.30	--
b	0.33	0.51	--
c	0.229	0.318	--
D	10.11	10.46	10.29
E	10.01	10.64	10.33
E1	7.42	7.59	7.52
e	--	--	1.27
h	--	--	0.48
L	0.41	1.27	--
Ø	0°	8°	--
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/_files/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
C	1.27
C1	5.20
X	0.60
Y	2.20

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.

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A. Life support devices or systems are devices or systems which:

1. are intended to implant into the body, or

2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.

B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

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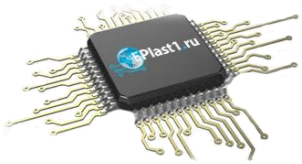
Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits,General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

Телефон: 8 (812) 309 58 32 (многоканальный)
Факс: 8 (812) 320-02-42
Электронная почта: org@eplast1.ru
Адрес: 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.